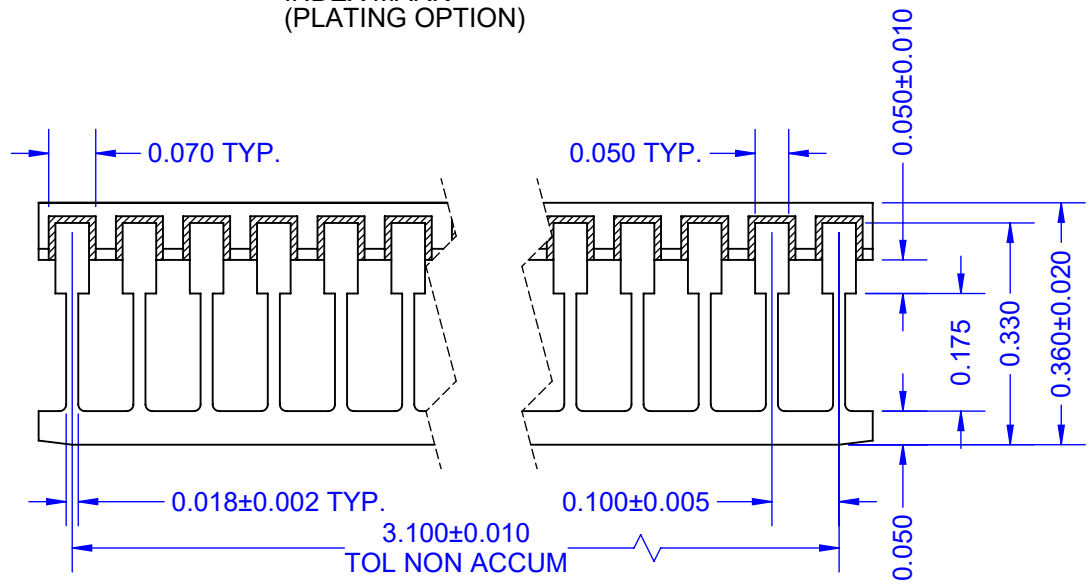


DETAIL B
SCALE 8 : 1

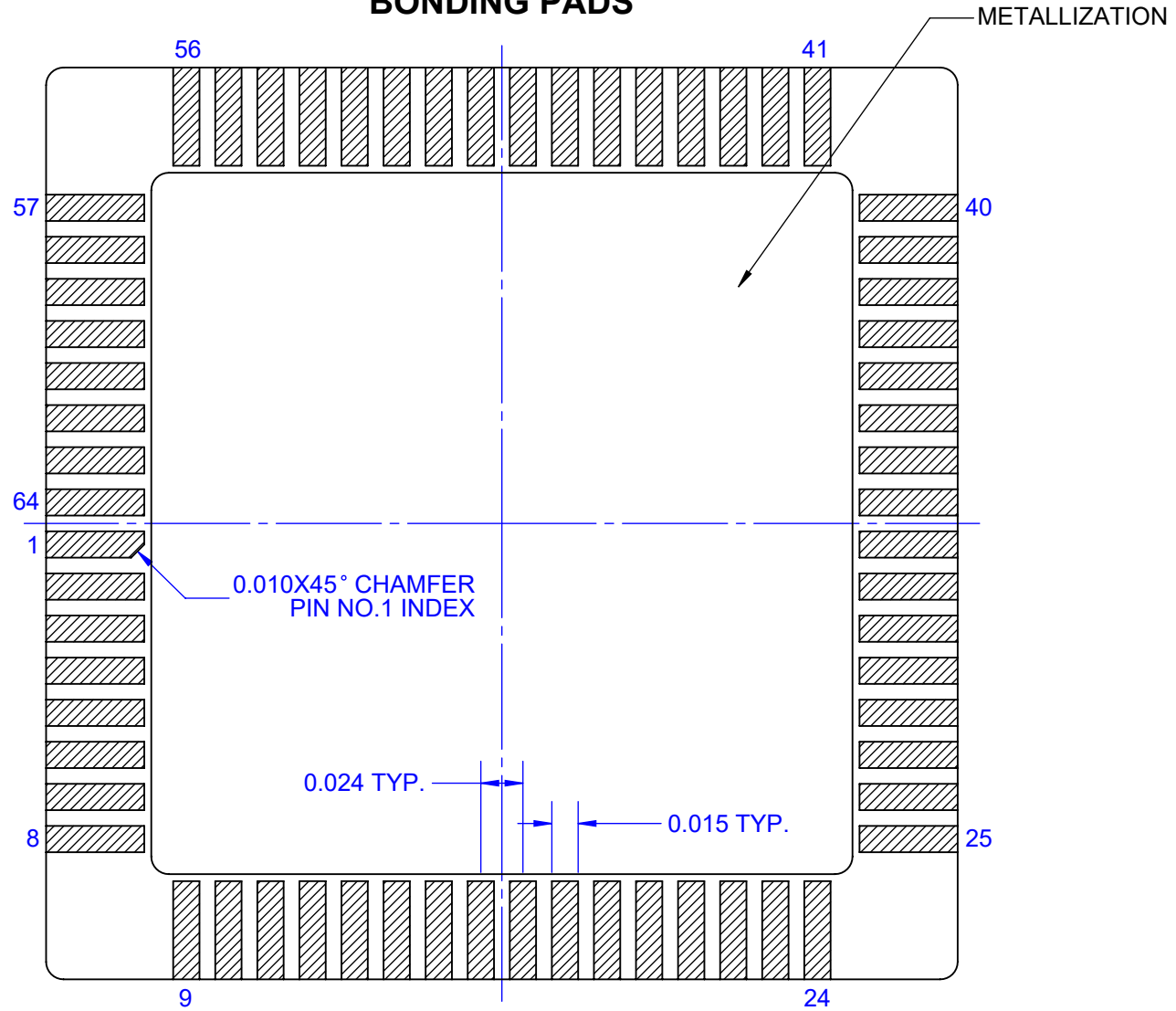


- NOTES:
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.35 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP64F9-N400	GOLD	168762

APPROVALS	DATE	TopLine®			
DRAWN T. Au	11/04/16				
ENG M. Hart	11/04/16	TITLE CERDIP64F9-N400 DIE PAD 400 MIL (10.1mm) SQ			
MFG		SCALE 2:1	SIZE A	DRAWING NO. 168762	REV A
QA		DO NOT SCALE DRAWING			SHEET 1 OF 4
CUST					
REVISED					

BONDING PADS



TopLine®

TITLE CERDIP64F9-N400
DIE PAD 400 MIL (10.1mm) SQ

SCALE 10:1	SIZE A	DRAWING NO. 168762	REV A
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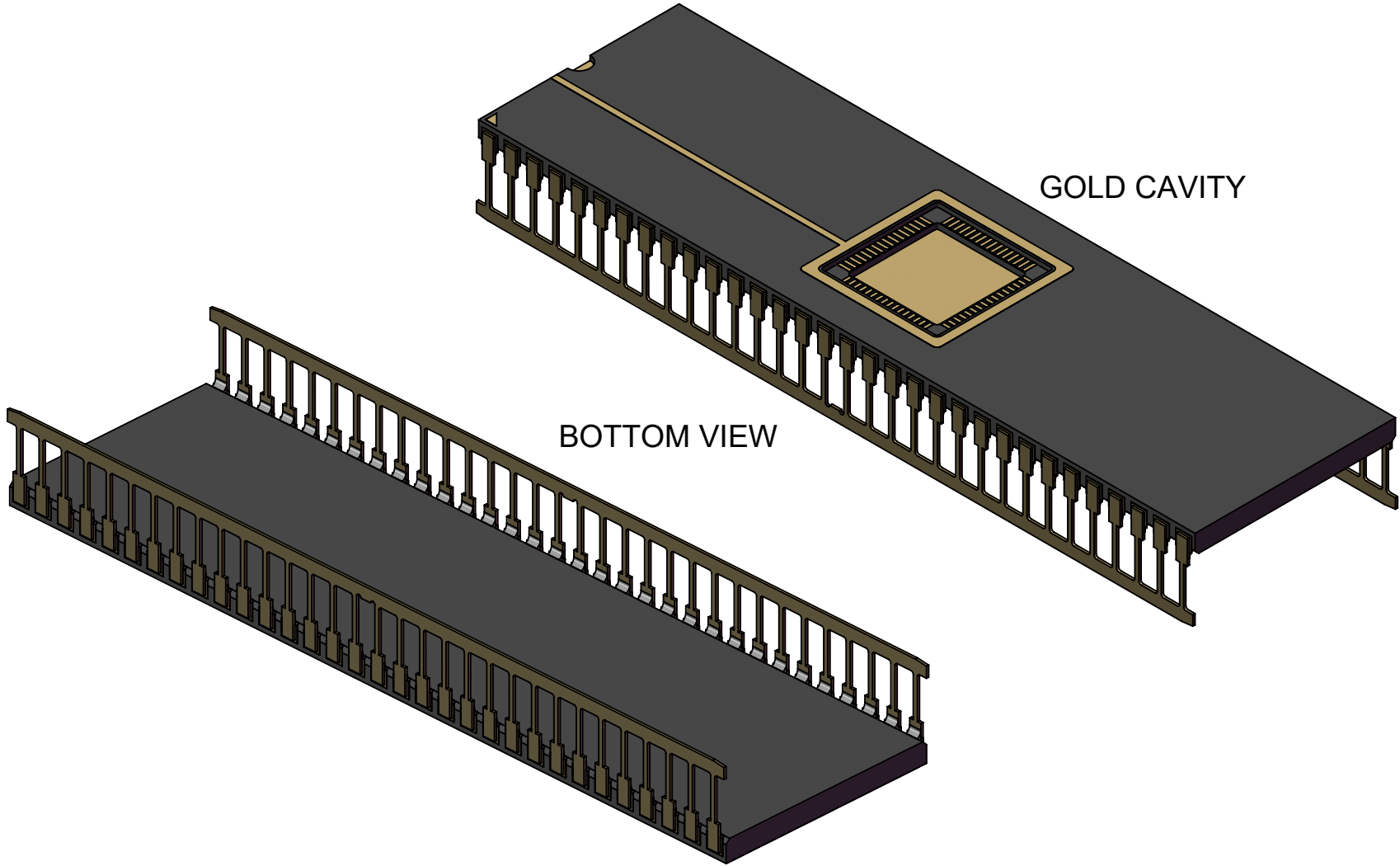
DO NOT SCALE DRAWING

SHEET 2 OF 4

PART NUMBER TABLE

PART NUMBER	DIE PAD	DWG
CERDIP64F9-N400	GOLD	168762

MODELS

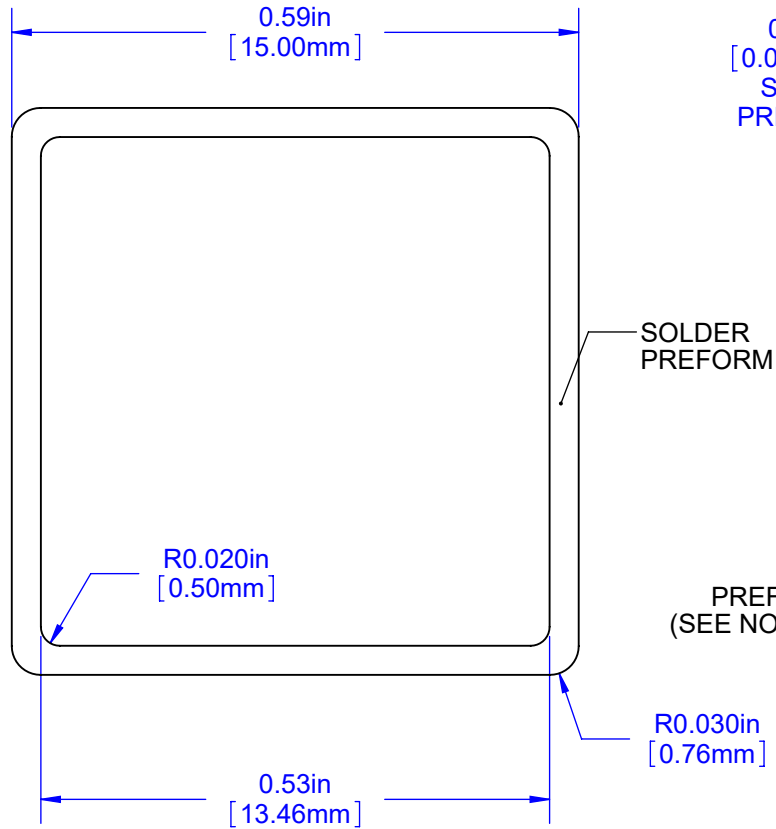


PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP64F9-N400	GOLD	168762

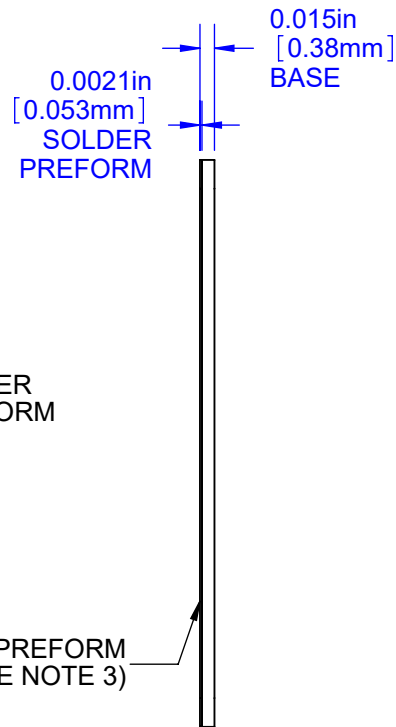
TopLine[®]			
TITLE CERDIP64F9-N400 DIE PAD 400 MIL (10.1mm) SQ			
SCALE 2.5:1	SIZE A	DRAWING NO. 168762	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 4

COMBO LID

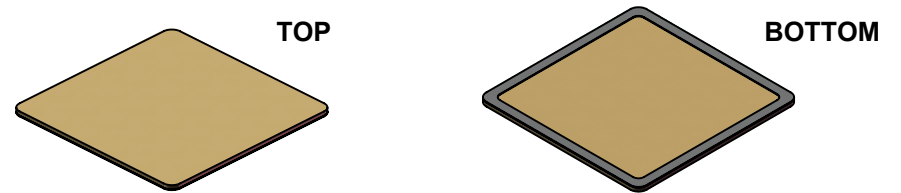
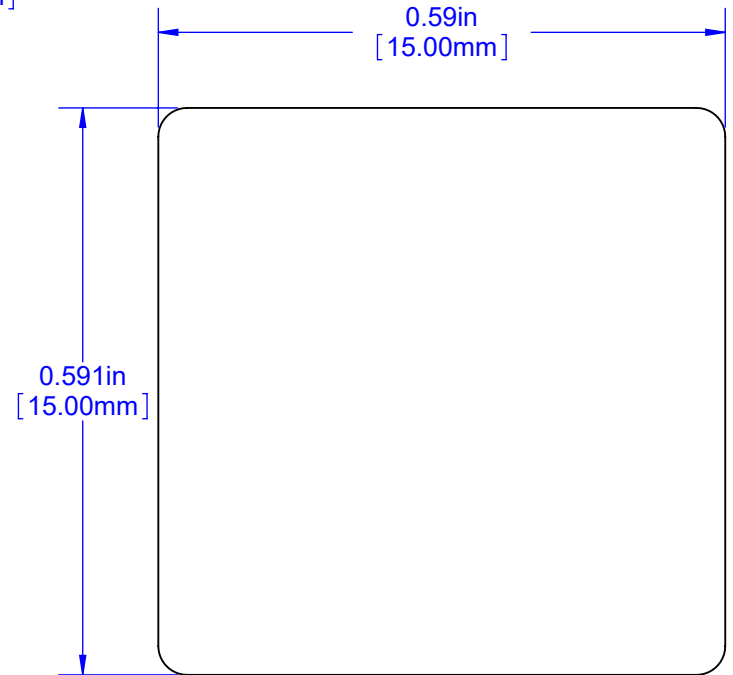
BOTTOM



SIDE



TOP



MODEL

NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ±1.0 Sn 20%.
4. FLATNESS 1.0 MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

TopLine®

TITLE		CL-590SQ-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	165901	A
DO NOT SCALE DRAWING		SHEET 4 OF 4	